EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	1	("5422435").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/02 11:07
L18	1	("6876088").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/02 15:26
L19	0	("2001011766").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/02 15:26
L20	1	("20010011766").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/02 15:48
L21	1	("20030015803").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/02 16:33
L22	1	("20040173885").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/02 16:33
S1	1	("20040173885").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/02/28 09:48
S2	1929	(257/672,696,E23.037,E23.052). CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/02/24 10:52
S3	1	("6777786").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/02/23 19:02
S4	1	("6781243").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/02/23 19:02
S7	1	("6841469").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/02/27 17:00
S8	1864	(257/686).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/02/27 13:58
S9	653	S8 and (chip integrated adj circuit die IC) and substrate and (non$conductive adj layer dielectric insulat$2 ILD IMD inter$level adj dieletric interm$metal adj dielectric)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/28 14:19
S11	4	((("5763939") or ("6101100") or ("5898220") or ("6137164")).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/01 20:11

S12	1	("6900528").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/02 11:07
S13	1	("6583503").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/02/27 20:52
S14	1	("20020125558").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/02/28 09:48
S15	1	("20030164540").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/02/28 10:58
S16	1	("6710246").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/02/28 11:05
S17	1	("6876088").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/02/28 11:05
S18	1867	(257/686).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/02/28 16:23
S20	2484	(257/692,698).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/02/28 14:42
S21	543	S20 and (chip integrated adj circuit die IC) and substrate and (non$conductive adj layer dielectric insulat$2 ILD IMD inter$level adj dieletric interm$metal adj dielectric) and (plate plating)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/28 14:43
S22	1867	(257/686).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/02/28 16:24
S23	994	S22 and substrate and (die IC integrated adj circuit chip) and (dielectric non$conductor insulat$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/28 18:08
S24	565	S22 and substrate and (die IC integrated adj circuit chip) and (dielectric non$conductor insulat$3) and (plat$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/28 16:25
S25	1	("20030015803").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/02/28 18:08